IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard  Form Type http://www.ipc.org/IPC-175x  Distribute				*	Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					als and Mfg Information			
upplier Infor									,						
Company name* Company u			ompany unio	ique ID Uni			Unique ID Authority				Respons	Response Date*			
nsemi											2023-06-08				
Contact Name		Tit	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stev	wards	Pro	Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Envi			roduct Envir	o Compliance	ce NA Product-Env-Stewar				ewards@onsemi.com						
Reques	ster Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	rsion Manufacturing Site			Weight*	UOM	Unit Type	
		AR0144ATS A0-TPBR	SM20XUE	1MP 1/4 CIS SO			2023-06-08		7	ΓΑ1	1	106.72	mg	Each	
<b>Ianufacturin</b>	g Proccess Informatio	n													
Terminal Plating / Grid Array Material Terminal Base			ninal Base A	lloy J	I-STD-020 MS	SL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles					eles				
SnAgCu		CU A	CU Alloy 3			260	C 30		secon	ds 3					
omments															
TTENTION: M	SL 3 Rated item requires B	Bake and Dry I	Pack (after	electrical test)											
or more informa	tion regarding material co	mposition plea	ase refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	16.35	mg		Misc.	proprietary data		0.0621	mg
			Supplier	Silicon (Si)	7440-21-3		16.126	mg
			Supplier	Aluminum (Al)	7429-90-5		0.1619	mg
Die Attach	1.35	mg		Bismaleimide Monomer	proprietary data		0.5197	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.0068	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.135	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.0068	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.135	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.135	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0068	mg
			Supplier	Other Additive Agents	Proprietary Data		0.27	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.135	mg
Ероху	1.03	mg	Supplier	Imidazole Addition	68490-66-4		0.309	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.103	mg
			Supplier	Zirconium Dioxide (ZrO2)	1314-23-4		0.103	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.103	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.412	mg
Imaging Lens	8.8	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.44	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		0.44	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.44	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		0.44	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.044	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.44	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		0.44	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		6.116	mg
Mold Compound	31.06	mg		Epoxy resin	proprietary data		7.7029	mg
			Supplier	Other Additive Agents	Proprietary Data		0.9939	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.106	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		18.3254	mg

			Supplier	Silica Crystalline (SiO2)	14808-60-7	0.9318	mg
Solder Ball	30.04	mg	Supplier	Silver (Ag)	7440-22-4	0.9012	mg
			Supplier	Tin (Sn)	7440-31-5	28.9886	mg
			Supplier	Copper (Cu)	7440-50-8	0.1502	mg
Solder Mask	1.92	mg		Epoxy resin	proprietary data	0.2304	mg
			Supplier	Acrylate	Proprietary Data	0.7334	mg
			Supplier	Talc	14807-96-6	0.0518	mg
			Supplier	Miscellaneous	Trade Secret	0.071	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	0.8333	mg
Substrate Copper Foil	1.47	mg	Supplier	Copper (Cu)	7440-50-8	1.47	mg
Substrate - Core Material	7.32	mg		Epoxy resin	proprietary data	4.2456	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	3.0744	mg
Substrate Plating-Au	0.17	mg	Supplier	Gold (Au)	7440-57-5	0.17	mg
Substrate Plating-Cu	6.6	mg	Supplier	Copper (Cu)	7440-50-8	6.6	mg
Substrate Plating-Ni	0.3	mg	В	Nickel (Ni)	7440-02-0	0.3	mg
Wire Bond - Au	0.31	mg	Supplier	Gold (Au)	7440-57-5	0.31	mg